

LTspice Model

IPM

Mitsubishi

SLIMDIP-L

Model Information

Model A macro model
Call Name MDC_SLIMDIP-L_LT
Pin Assign 1:NC 2:VUFS 3:VUFB 4:VVFS 5:VVFB 6:VWFS 7:VWFB 8:UP 9:VP 10:WP 11:VP1
 12:VNC 13:UN 14:VN 15:WN 16:VN1 17:FO 18:CIN 19:VNC2 20:VOT 21:NW 22:NV
 23:NU 24:W 25:V 26:U 27:P
File List Model Library MDC_SLIMDIP-L_LT01.lib
 Model Report MDC_SLIMDIP-L_LT.pdf(this file)

Verified Simulator Version LTspiceXVII

Note

References

The information which was used for modeling is as follow:

[Data Sheet]

- Date/Version 2021.1
- Product name SLIMDIP-L
- Company name Mitsubishi Electric Corporation

[Characteristics listed]

- Characteristics Switching_Lower, Switching_Upper
 UVLO_N, UVLO_P, VITH_N, VITH_P
 FWD,Function

Simulation Condition

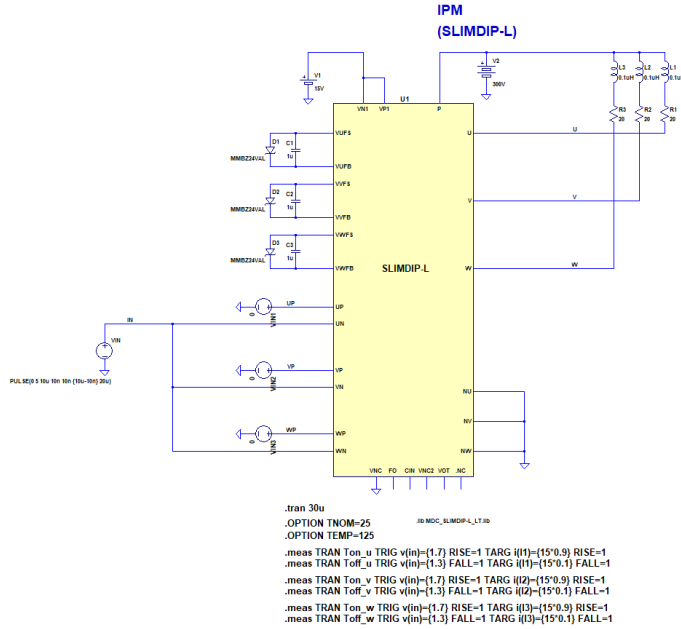
This table shows the range of evaluated simulation range that was not occurs any convergence problems in this area.

Item	Condition	Unit
Temperature	25	deg C

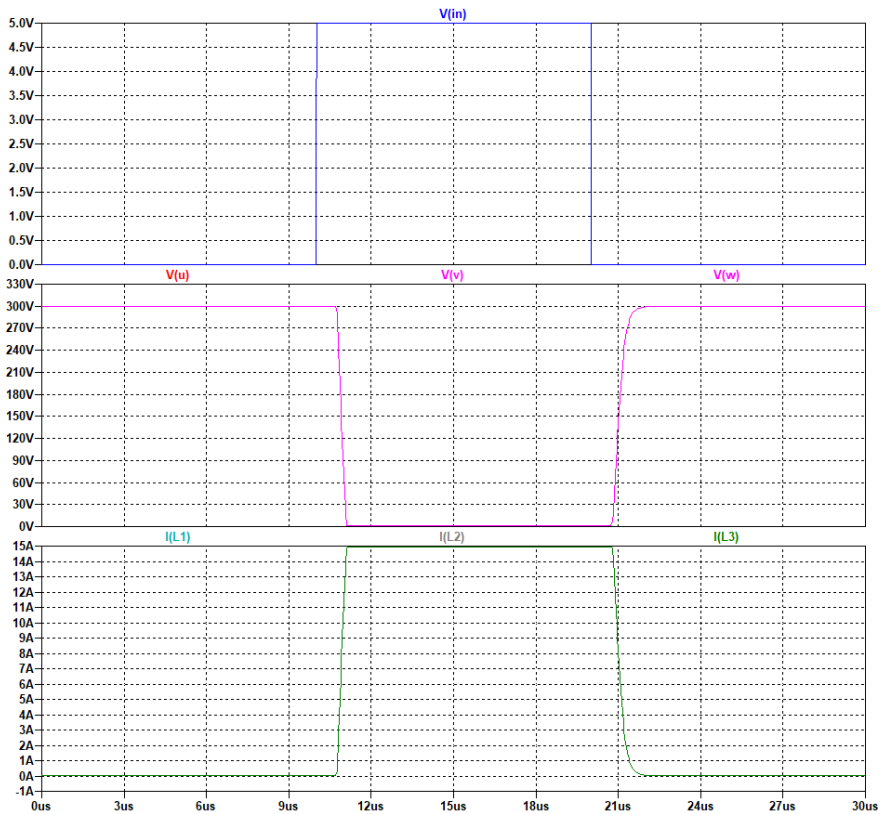
Model Functions Table

Functions	Implemented
Switching_Lower	○
Switching_Upper	○
UVLO_N	○
UVLO_P	○
VITH_N	○
VITH_P	○
FWD	○
Function	○

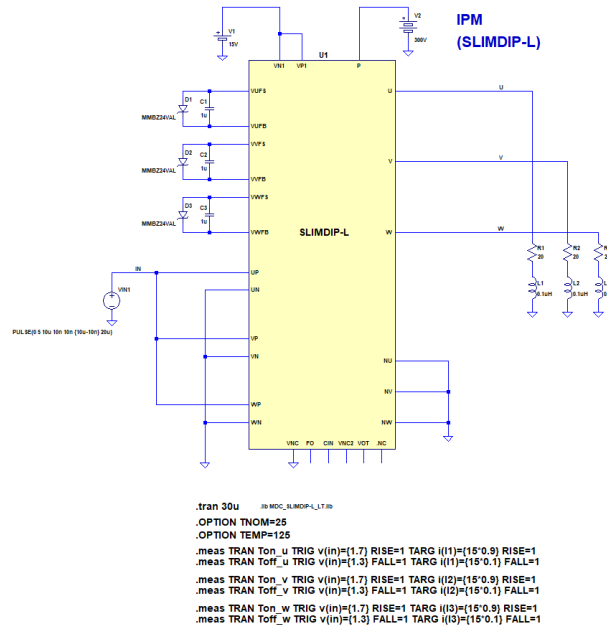
Switching_Lower
Testbench



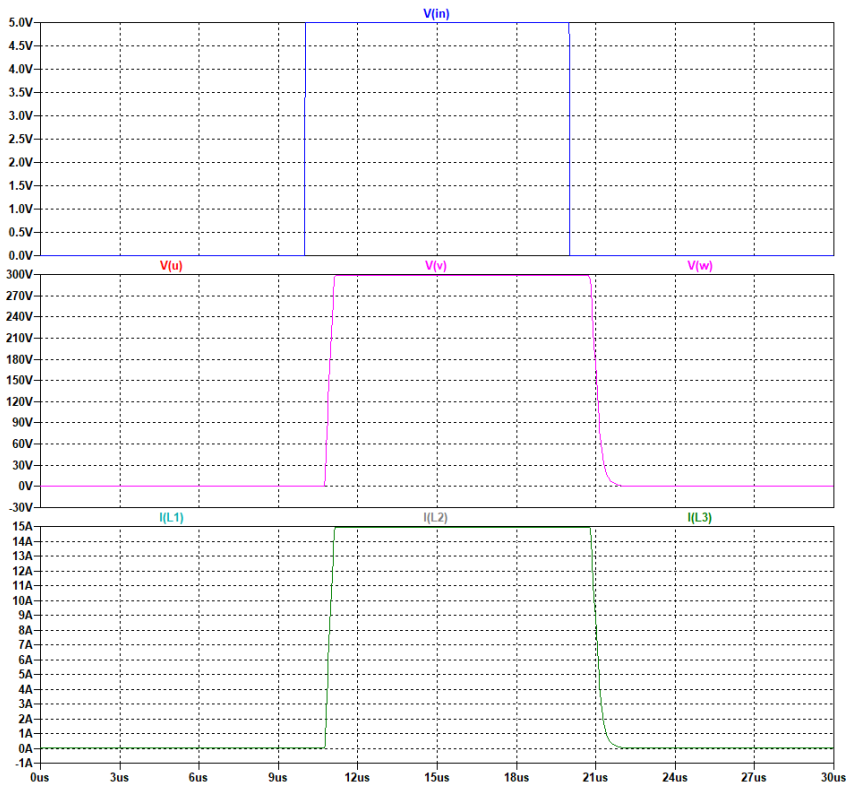
Simulation results are following.
Explanatory notes — : simulated



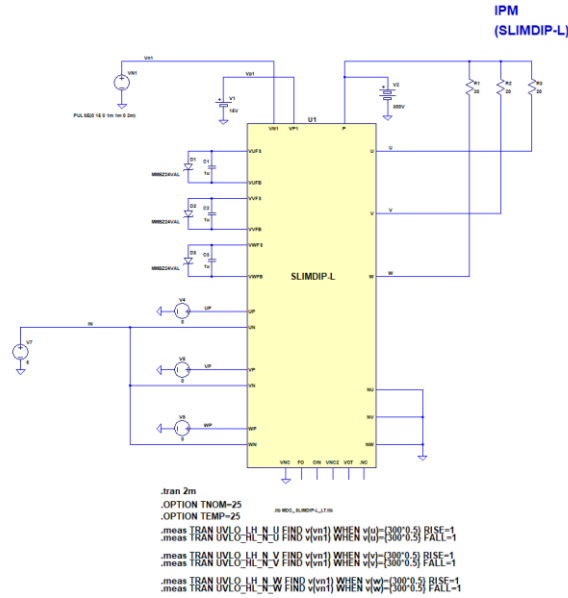
Switching_Upper
Testbench



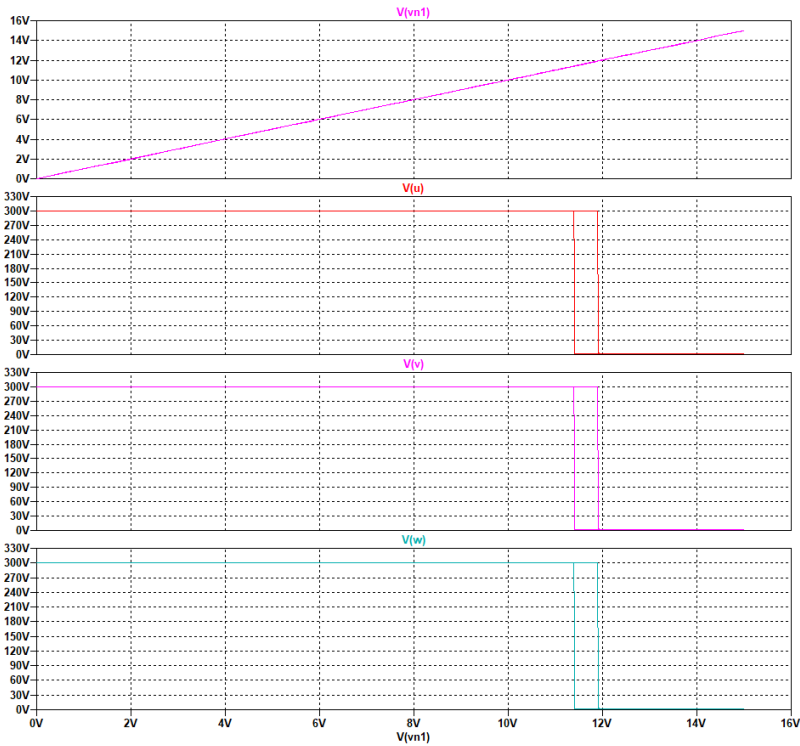
Simulation results are following.
Explanatory notes — : simulated



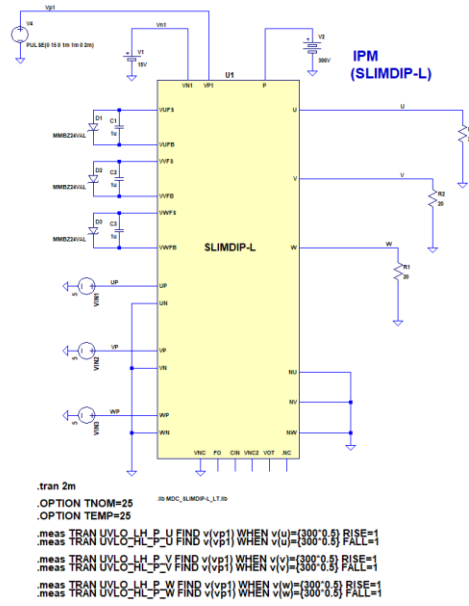
UVLO_N
Testbench



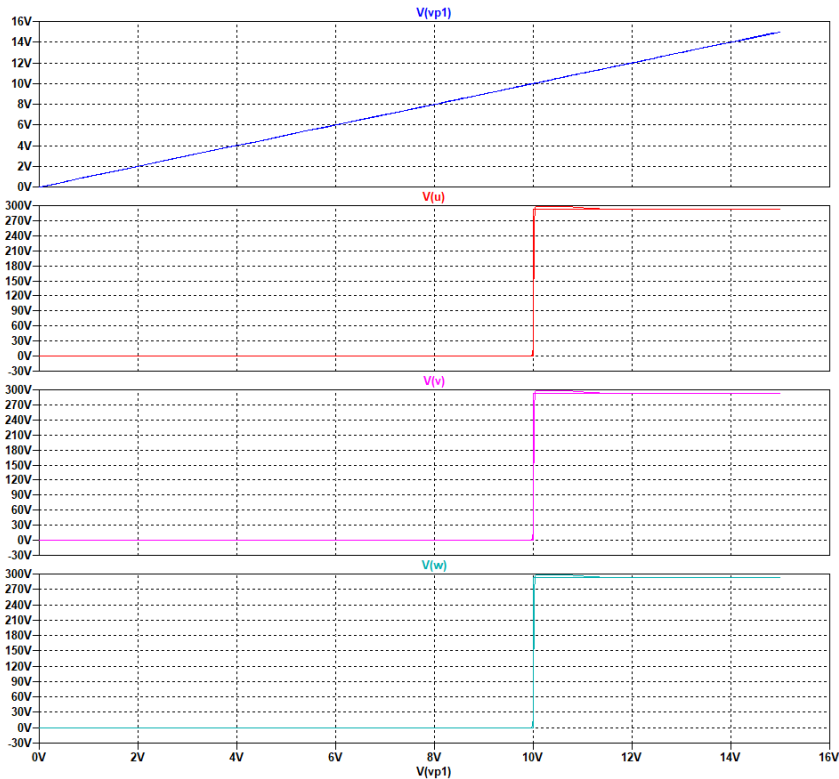
Simulation results are following.
Explanatory notes — : simulated



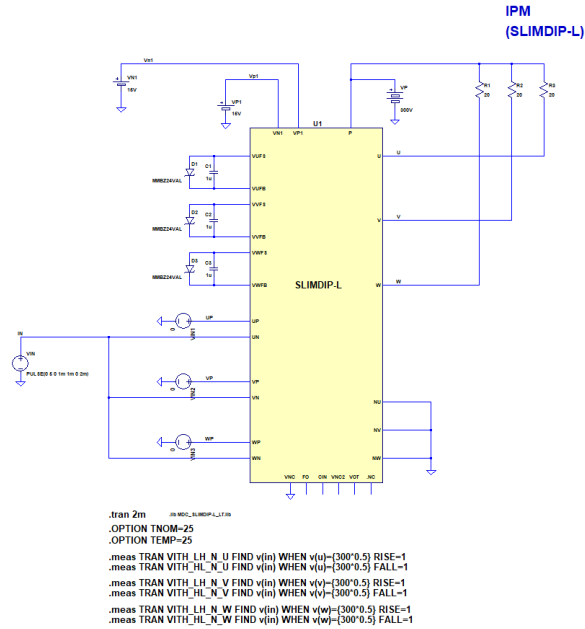
UVLO_P
Testbench



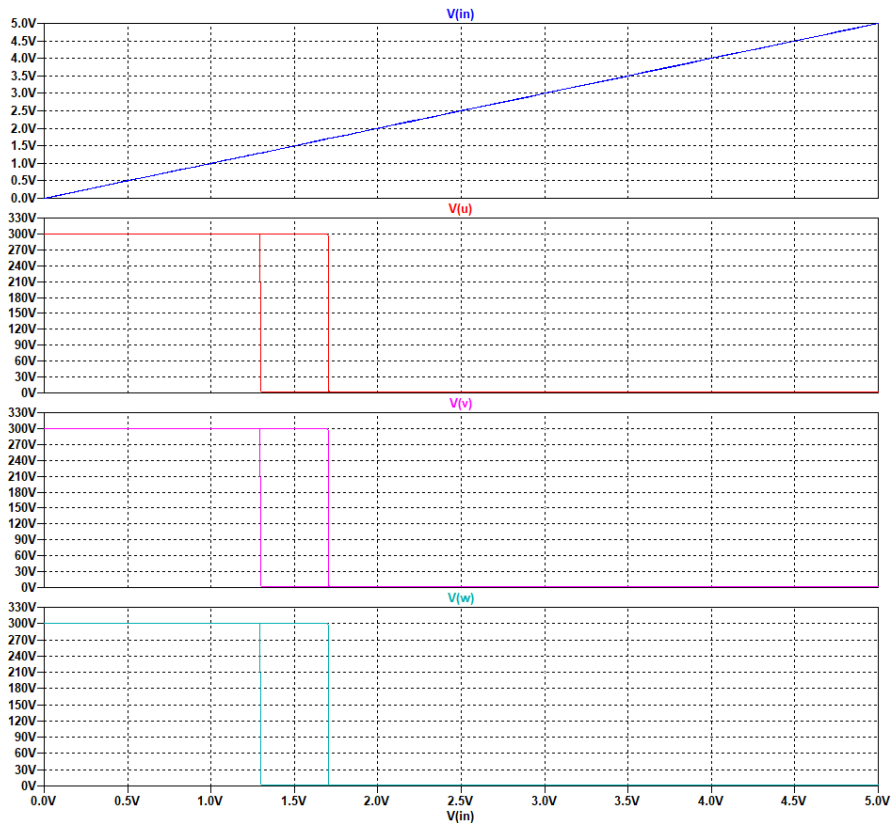
Simulation results are following.
Explanatory notes — : simulated



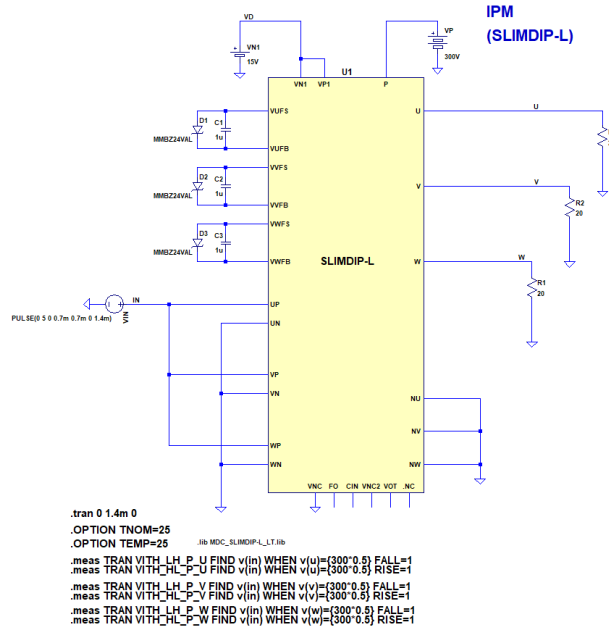
VITH_N
Testbench



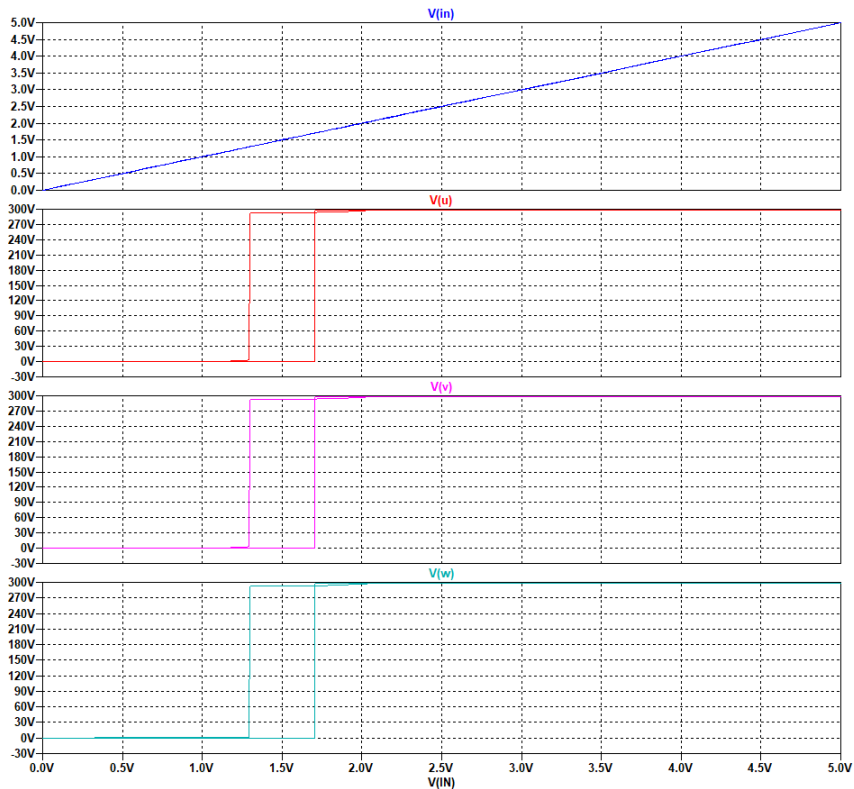
Simulation results are following.
Explanatory notes — : simulated



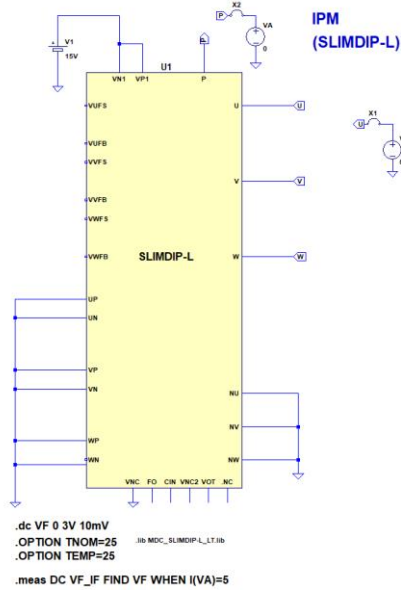
VITH_P
Testbench



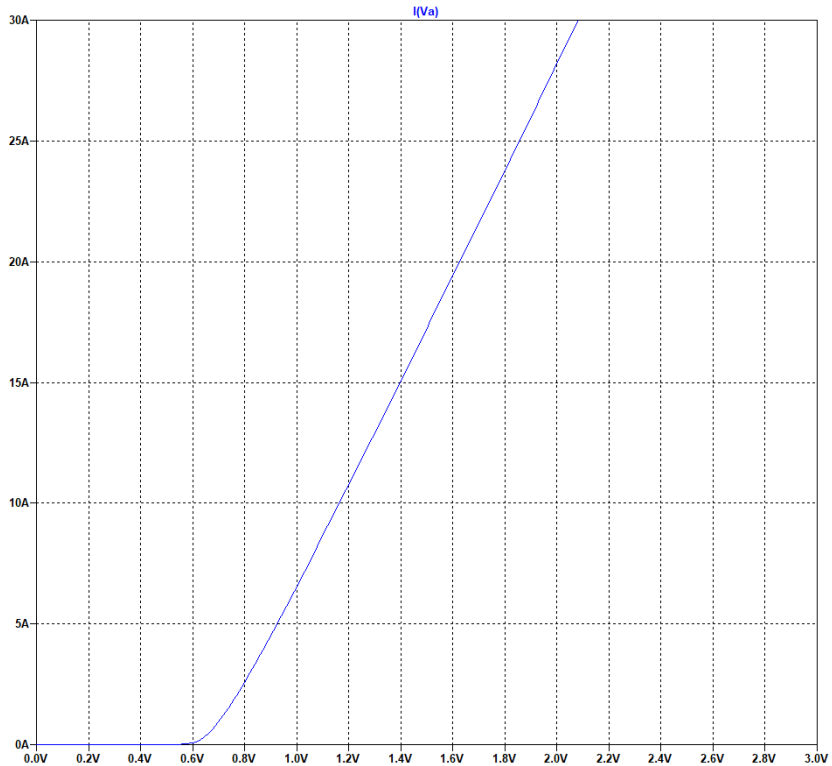
Simulation results are following.
Explanatory notes — : simulated



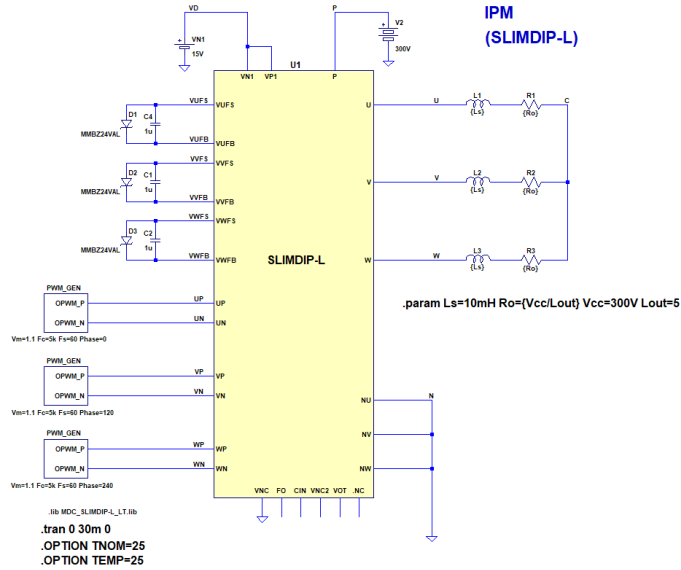
FWD
Testbench



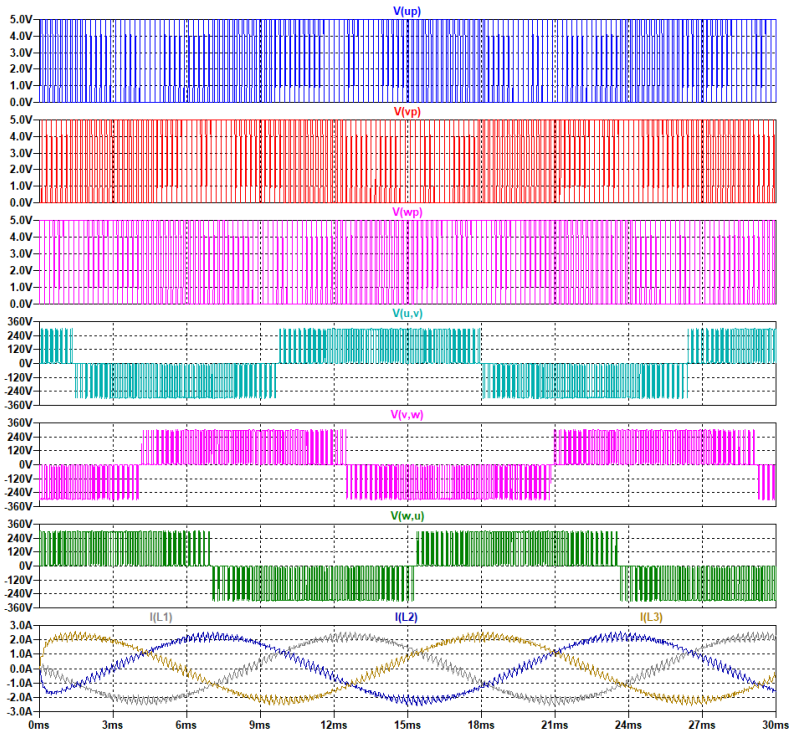
Simulation results are following.
Explanatory notes — : simulated



Function
Testbench



Simulation results are following.
Explanatory notes — : simulated



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